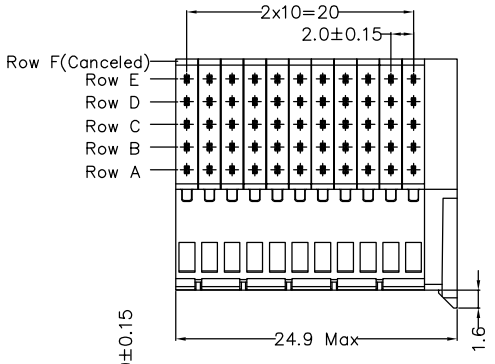
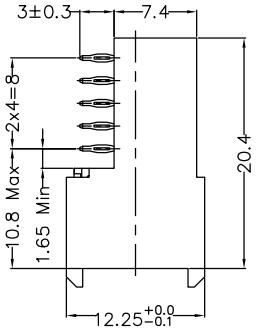
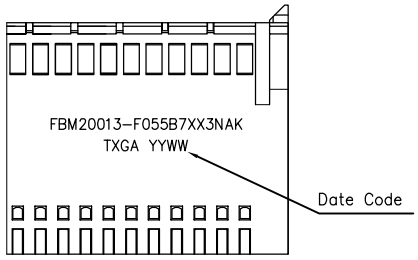
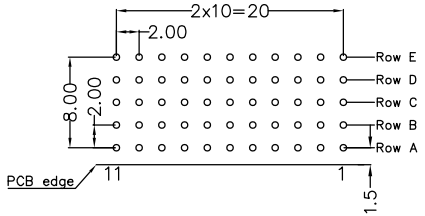
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD









Recommended P.C.Board Layout
Tolerances: ±0.05

SPECIFICATIONS

Electrical Performances
- Current Rating: 1.0A AC(rms)/DC
- Voltage Rating: 500V AC(rms)/DC
- Contact Resistance: 20 mΩ Max
- Insulation Resistance: 10000 MΩ MIN
- Withstanding Voltage: 750V AC r.m.s

Material and Plating
- Housing: LCP (UL 94V-0)
- Rear Bracket: PBT (UL 94V-0)
- Contact: Copper alloy/Gold plated on contact area and matte tin plated on tails,nickel under plated over all

Environmental Characteristics
- Temperature Range-Operating: -55°C~+125°C
- Storage temperature : -40°C~+70°C

Ordering Information

FBM	200	13	—	F	055	B	7	XX	3	NA	K
1	2	3		4	5	6	7	8	9	10	11

1	Category	2	Series Number	3	Distinction No.	4	Gender	5	Circuits	6	Entry Angle
	FBM-HM Back plane connector		200-Pitch2.0mm		13		F-Female		055		B-90° Angle

7	Plating	8	Thickness of Plating	9	Material-Resin	10	Color-Resin	11	Packaging
	7-Selective gold plated on contact area and matte tin plated on tails		00-Gold flash 01-0.025μm 03-0.075μm Custom plate available		3-LCP		NA-Natural		K-Tray

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	TXGA Building Technology Cornerstone
	GB 1804-m	X.° ±5°	LEO	13/SEP/22	FBM20013-F055B7XX3NAK	FBM20013	
DESIGN UNITS METRIC(mm)	30~120 ±0.30	X.X° ±2°	CHECKED BY	DATE	TITLE		REV 0 / SHEET NO. 1/1
	6~30 ±0.20	X.XX° ±1°	GISELLE	13/SEP/22	HM Back plane connector Pitch 2.0mm Female(Press fit)		
SCALE 1.5:1 / SIZE A4	0~6 ±0.10	X.XXX° ±0.5°	DRAWN BY HJP	DATE 13/SEP/22	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		